EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	12	yoshiyuki near3 wada.in. and component and adhesive	US-PGPUB; USPAT; EPO; JPO	OR	ON	2008/09/08 15:20
S2	9	("20020058743" | "4388132" | "4818812" | "5308980" | "6255376" | "6255738" | "6376907" | "6387734" | "6617675").PN. OR ("7071577").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/09/08 15:22
S3	23	tadahiko near2 sakai.in. and component and adhesive not S1	US-PGPUB; USPAT; EPO; JPO	OR	ON	2008/09/08 15:23
S4	101	("5764485" "5532070" "4885841" "5282565" "5597110" "5784777" "5806753" "5873512" "4611397" "4776508" "4928387" "4932876" "4965927" "5184767" "5199165" "5332144" "5353980" "5393489" "5457538" "5526563" "5527481" "5571034" "5591941" "5614328" "5620131" "5646826" "5653601" "5726861" "5820014" "5850693" "5868304" "5868302" "5877937" "5918794" "5961032" "5987358" "5985043" "6070782" "6079099" "6095857" "6108210" "6181544" "6229124" "6229248" "6232558" "4262300" "4269870" "4323631" "4381601" "4412641" "4491084" "4499120" "4501064" "4542442" H000498 "4782991" "4795670" "4821946" "4829553" "4829664" "4830263" "4835345"	US-PGPUB; USPAT; EPO; JPO	OR	ON	2008/09/08 15:24

		"4870356" "4872261" "4872606" "4874907" "4894509" "4959750" "4958588" "4979290" "4985310" "5010246" "5012388" "5236117" "5250809" "5275330" "5295214" "5296046" "5307983" "5315486" "5320272" "5326390" "5328660" "5344592" "5368814" "5373985" "5385290" "5386345" "5397871" "5454505" "5457880" "5531942" "5560100" "5564183" "5569880" "5607097" "5613633" "5627433" "5632630" "5663526"). pn.				
S5	8	("4679118" | "5037782" | "5295043" | "5500785" | "5548090" | "5914859" | "5920458").PN. OR ("6232558").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/09/08 15:30
S6	932	(print$3 wiring circuit) near3 (board substrate) and (ic chip semiconductor ((electrical electronic) near4 (part component device element))) and solder$3 and solder with thermosetting	US-PGPUB; USPAT; EPO; JPO	OR	ON	2008/09/08 16:41
S7	638	(print$3 wiring circuit) near3 (board substrate) same(ic chip semiconductor ((electrical electronic) near4 (part component device element))) same solder$3 and solder with thermosetting	US-PGPUB; USPAT; EPO; JPO	OR	ON	2008/09/08 16:41
S8	64	S7 and "29"/$.ccls.	US-PGPUB; USPAT; EPO; JPO	OR	ON	2008/09/08 16:41

S9	57	S7 and "228"/$ not S8	US-PGPUB; USPAT; EPO; JPO	OR	ON	2008/09/08 16:46
S10	36	(print$3 wiring circuit) near3 (board substrate) same(ic chip semiconductor ((electrical electronic) near4 (part component device element))) same solder$3 and solder with thermosetting with (mix $3 mixture)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2008/09/08 16:51
S11	80	("3818279" | "4190855" | "4604644").PN. OR ("4970575").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/09/08 16:55
S12	25	("20010019075" | "20020195170" | "20030051770" | "20030077478" | "20040151885" | "20040250919" | "20050039824" | "20050056687" | "20050056687" | "20060043597" | "5062896" | "5167729" | "5376403" | "5851311" | "5904782" | "6402013" | "6402013" | "6592020" | "6607825" | "6641679" | "6673858" | "6693162" | "6915944" | "6916538" | "7022266" | "7022410" | "7025906").PN.	US-PGPUB; USPAT; EPO; JPO	OR	ON	2008/09/08 16:59
S13	11	("20010019075" | "20020195170" | "20030051770" | "20050039824" | "20050056687" | "5062896" | "5376403" | "5904782" | "6402013" | "6524721" | "6592020").PN.	US-PGPUB; USPAT; EPO; JPO	OR	ON	2008/09/08 17:01

S14	22	("4312692" | "4680226" | "5071787" | "5074947" | "5084961" | "5086558" | "5283947" | "5384952" | "5477419" | "5545281" | "5757078" | "5843251").PN. OR ("6209196").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/09/08 17:23
S15	22	("4312692" | "4680226" | "5071787" | "5074947" | "5084961" | "5086558" | "5283947" | "5384952" | "5477419" | "5545281" | "5757078" | "5843251").PN. OR ("6209196").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/09/08 17:24
S16	8	("3610870" | "5414928").PN. OR ("5669137").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/09/08 17:26
S17	1309	(print$3 wiring circuit) near3 (board substrate) same(ic chip semiconductor ((electrical electronic) near4 (part component device element))) same solder$3 and solder with (epoxy resin thermosetting underfill encapsulant) with (mix$3 mixture paste) not S10	US-PGPUB; USPAT; EPO; JPO	OR	ON	2008/09/08 17:37
S18	68	(print$3 wiring circuit) near3 (board substrate) same(ic chip semiconductor ((electrical electronic) near4 (part component device element))) same solder$3 and solder near3 particle with (epoxy resin thermosetting underfill encapsulant) with (mix$3 mixture paste) not S10	US-PGPUB; USPAT; EPO; JPO	OR	ON	2008/09/08 17:37

S19	325	(print$3 wiring circuit) near3 (board substrate) same(ic chip semiconductor ((electrical electronic) near4 (part component device element))) same solder$3 and solder with (epoxy resin thermosetting underfill encapsulant) with (mix$3 mixture) not S10 not S18	US-PGPUB; USPAT; EPO; JPO	OR	ON	2008/09/08 17:40
S20	32	S19 and "29"/$.ccls.	US-PGPUB; USPAT; EPO; JPO	OR	ON	2008/09/08 17:42
S21	38	S19 and "228"/$ not S20	US-PGPUB; USPAT; EPO; JPO	OR	ON	2008/09/08 17:44
S22	19	("4172547" | "4208005" | "4312692" | "4345371" | "4398660" | "4578426" | "4595606" | "5102030" | "5254412").PN. OR ("5447267").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/09/08 17:47
S23	66	S19 and "438"/$ not S20 not S21	US-PGPUB; USPAT; EPO; JPO	OR	ON	2008/09/08 17:48
S24	23	("5014111" | "5668059" | "5717477").PN. OR ("5981313").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/09/08 17:53
S25	133	(print$3 wiring circuit) near3 (board substrate) and (ic chip semiconductor ((electrical electronic) near4 (part component device element))) with (reflow$3 solder$3) and solder near3 (particle powder paste) with (epoxy resin thermosetting underfill encapsulant) with (mix$3 mixture)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2008/09/08 18:18

S26	6	(print$3 wiring circuit) near3 (board substrate) and (ic chip semiconductor ((electrical electronic) near4 (part component device element))) with (reflow$3 solder$3) and solder near3 (particle powder paste) with (epoxy resin thermosetting underfill encapsulant) with (mix$3 mixture blend$3) not S25	US-PGPUB; USPAT; EPO; JPO	OR	ON	2008/09/08 18:23
S27	26	(ic chip semiconductor ((electrical electronic) near4 (part component device element))) with (reflow$3 solder$3) and solder near3 (particle powder paste) with (epoxy resin thermosetting underfill encapsulant) with (mix$3 mixture blend$3) not S25 not S26	US-PGPUB; USPAT; EPO; JPO	OR	ON	2008/09/08 18:36
S28	86	solder near3 (particle powder paste) with (epoxy resin thermosetting underfill encapsulant) with (mix$3 mixture blend$3) not S25 not S26 not S27	US-PGPUB; USPAT; EPO; JPO	OR	ON	2008/09/08 18:38
S29	775	solder with (epoxy resin thermosetting underfill encapsulant) with (mix$3 mixture blend$3) not S25 not S26 not S27 not S28	US-PGPUB; USPAT; EPO; JPO	OR	ON	2008/09/08 18:47
S30	111	solder with (epoxy resin thermosetting underfill encapsulant) with (mix$3 mixture blend$3) and (reflow$3 solder$3) with separat$3 not S25 not S26 not S27 not S28	US-PGPUB; USPAT; EPO; JPO	OR	ON	2008/09/08 18:48

S31	142	(((metal$3 conduct$3) near3 particle) solder) with (epoxy resin thermosetting underfill encapsulant) with (mix $3 mixture blend$3) and (reflow$3 solder $3) with separat$3 and (board substrate) with (land pad terminal) and (ic chip ((electronic electrical) near3 (component part element device)))	US-PGPUB; USPAT; EPO; JPO	OR	ON	2008/09/12 17:34
S32	165	(solder sn$1bi) with (epoxy resin thermosetting underfill encapsulant) with (mix $3 mixture blend$3) and (solder sn$1bi) with (reflow$3 solder $3) same (cure curing cured) with (epoxy resin thermosetting underfill encapsulant) and (ic chip ((electronic electrical) near3 (component part element device))) not S31	US-PGPUB; USPAT; EPO; JPO	OR	ON	2008/09/12 17:44
S33	10	(solder sn$1bi) with (epoxy resin thermosetting underfill encapsulant) with (mix $3 mixture blend$3) and (solder sn$1bi) with (reflow$3 melt$3) same (cure curing cured) with (epoxy resin thermosetting underfill encapsulant) not S31 not S32	US-PGPUB; USPAT; EPO; JPO	OR	ON	2008/09/12 17:49
S34	5	("20020185306" | "20050056687" | "20060043597" | "20070175969" | "6402013").PN.	US-PGPUB; USPAT; EPO; JPO	OR	ON	2008/09/12 17:57

S35	17	("5167729" | "5215601" | "5741622" | "5830389" | "5851311" | "5989362" | "6220501").PN. OR ("6402013").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/09/12 17:59
S36	11	("20010019075" | "20020195170" | "20030051770" | "20050039824" | "20050056687" | "5062896" | "5376403" | "5904782" | "6402013" | "6524721" | "6592020").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/09/12 18:00
S37	25	("20010019075" | "20020195170" | "20030051770" | "20030077478" | "20040151885" | "20040250919" | "20050039824" | "20050056687" | "20050056687" | "20060043597" | "5062896" | "5167729" | "5376403" | "5851311" | "5904782" | "6402013" | "6402013" | "6592020" | "6607825" | "6641679" | "6673858" | "6693162" | "6915944" | "6916538" | "7022266" | "7022410" | "7025906").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/09/12 18:02
S38	17	("5167729" | "5215601" | "5741622" | "5830389" | "5851311" | "5989362" | "6220501").PN. OR ("6402013").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/09/14 08:57
S39	10	("4545610" | "5173670" | "5266748").PN. OR ("5726861").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/09/14 09:04

S40	36	("4746557" | "4801904" | "4810983" | "4904967" | "4918570" | "5051712").PN. OR ("5173670").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/09/14 09:05
S41	12	("4339785" | "4573105" | "4833570" | "5111991" | "5129573" | "5155904" | "5489752" | "5726861").PN. OR ("5886878").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/09/14 09:06
S42	36	("2441960" | "3272909" | "3410949" | "4208005").PN. OR ("4339785").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/09/14 09:07
S43	10	("4339785" | "5085364" | "5128746" | "5493259" | "5529957" | "5814401" | "6071371" | "6202917" | "6303872" | "6521997").PN. OR ("7408264").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/09/14 09:08
S44	22	("3991347" | "4389771" | "4801489" | "4806706" | "4933305" | "4967313").PN. OR ("5266748").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/09/14 09:13
S45	20	("4132341" | "4295183" | "4755631" | "4767892" | "4893216" | "4965702" | "5266748").PN. OR ("5386087").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/09/14 09:14
S46	26	("5243140" | "5357060" | "5381307" | "5386087" | "5453581" | "5670750" | "5683788" | "5707714" | "5900674" | "5961737").PN. OR ("6115262").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/09/14 09:15

S47	36	("2700150" | "2902629" | "2981868" | "3061760" | "3141998" | "3290761" | "3531579" | "3626081").PN. OR ("3991347").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/09/14 09:18
S48	16	("5311405" | "6150193" | "6177731" | "6228466" | "6245594" | "6294840" | "6388335" | "6448644").PN. OR ("6521997").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/09/14 09:19
S49	9	("5266748" | "6084782" | "6153930" | "6338767" | "6515842" | "6521997" | "6566611" | "6774493" | "6836022").PN. OR ("7205485").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/09/14 09:20
S50	1	"6915944".pn.	US-PGPUB; USPAT; EPO; JPO	OR	ON	2008/09/14 23:21
S51	1	"6768197".pn.	US-PGPUB; USPAT; EPO; JPO	OR	ON	2008/09/14 23:22
S52	1	"5167729".pn.	US-PGPUB; USPAT; EPO; JPO	OR	ON	2008/09/14 23:23

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